Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NTD20N03L27, NVD20N03L27

Power MOSFET

20 A, 30 V, N–Channel DPAK

This logic level vertical power MOSFET is a general purpose part that provides the “best of design” available today in a low cost power package. Avalanche energy issues make this part an ideal design in. The drain–to–source diode has a ideal fast but soft recovery.

Features

- Ultra–Low $R_{DS(on)}$, Single Base, Advanced Technology
- SPICE Parameters Available
- Diode is Characterized for use in Bridge Circuits
- I_{DSS} and $V_{DS(on)}$ Specified at Elevated Temperatures
- High Avalanche Energy Specified
- ESD JEDAC rated HBM Class 1, MM Class A, CDM Class 0
- NVD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free and are RoHS Compliant

Typical Applications

- Power Supplies
- Inductive Loads
- PWM Motor Controls
- Replaces MTD20N03L in many Applications

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain–to–Source Voltage	V_{DSS}	30	Vdc
Drain–to–Gate Voltage (R_{GS} = 1.0 MΩ)	V_{DGR}	30	Vdc
Gate–to–Source Voltage – Continuous – Non–Repetitive ($t_p \le 10$ ms)	 V_{GS} V_{GS}	 ±20 ±24	Vdc
Drain Current – Continuous @ T_A = 25°C – Continuous @ T_A = 100°C – Single Pulse ($t_p \le 10$ μs)	 I_D I_D I_{DM}	 20 16 60	 Adc Apk
Total Power Dissipation @ T_A = 25°C Derate above 25°C Total Power Dissipation @ T_C = 25°C (Note 1)	P_D	74 0.6 1.75	W W/°CW
Operating and Storage Temperature Range	T_J, T_{stg}	–55 to 150	°C
Single Pulse Drain–to–Source Avalanche Energy – Starting T_J = 25°C (V_{DD} = 30 Vdc, V_{GS} = 5 Vdc, L = 1.0 mH, $I_{L(pk)}$ = 24 A, V_{DS} = 34 Vdc)	E_{AS}	288	mJ
Thermal Resistance – Junction–to–Case – Junction–to–Ambient – Junction–to–Ambient (Note 1)	 $R_{\theta JC}$ $R_{\theta JA}$ $R_{\theta JA}$	 1.67 100 71.4	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8″ from case for 10 seconds	T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. When surface mounted to an FR4 board using the minimum recommended pad size and repetitive rating; pulse width limited by maximum junction temperature.

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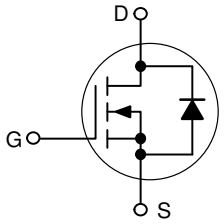
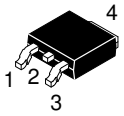
20 A, 30 V, $R_{DS(on)}$ = 27 mΩ

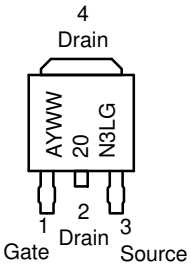
N–Channel





DPAK
CASE 369C
STYLE 2

MARKING DIAGRAM & PIN ASSIGNMENTS



A = Assembly Location*
20N3L = Device Code
Y = Year
WW = Work Week
G = Pb–Free Package

* The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain–to–Source Breakdown Voltage (Note 2)	$V_{(BR)DSS}$				Vdc
(V_{GS} = 0 Vdc, I_D = 250 μAdc)		30	–	–	
Temperature Coefficient (Positive)		–	43	–	mV/°C
Zero Gate Voltage Drain Current	I_{DSS}				μAdc
(V_{DS} = 30 Vdc, V_{GS} = 0 Vdc)		–	–	10	
(V_{DS} = 30 Vdc, V_{GS} = 0 Vdc, T_J =150°C)		–	–	100	
Gate–Body Leakage Current (V_{GS} = ±20 Vdc, V_{DS} = 0 Vdc)	I_{GSS}	–	–	±100	nAdc
ON CHARACTERISTICS (Note 2)					
Gate Threshold Voltage (Note 2)	$V_{GS(th)}$				Vdc
(V_{DS} = V_{GS}, I_D = 250 μAdc)		1.0	1.6	2.0	
Threshold Temperature Coefficient (Negative)		–	5.0	–	mV/°C
Static Drain–to–Source On–Resistance (Note 2)	$R_{DS(on)}$				mΩ
(V_{GS} = 4.0 Vdc, I_D = 10 Adc)		–	28	31	
(V_{GS} = 5.0 Vdc, I_D = 10 Adc)		–	23	27	
Static Drain–to–Source On–Voltage (Note 2)	$V_{DS(on)}$				Vdc
(V_{GS} = 5.0 Vdc, I_D = 20 Adc)		–	0.48	0.54	
(V_{GS} = 5.0 Vdc, I_D = 10 Adc, T_J = 150°C)		–	0.40	–	
Forward Transconductance (Note 2) (V_{DS} = 5.0 Vdc, I_D = 10 Adc)	g_{FS}	–	21	–	mhos
DYNAMIC CHARACTERISTICS					
Input Capacitance	(V_{DS} = 25 Vdc, V_{GS} = 0 Vdc, f = 1.0 MHz)	C_{iss}	–	1005	1260	pF
Output Capacitance		C_{oss}	–	271	420	
Transfer Capacitance		C_{rss}	–	87	112	
SWITCHING CHARACTERISTICS (Note 3)					
Turn–On Delay Time	(V_{DD} = 20 Vdc, I_D = 20 Adc, V_{GS} = 5.0 Vdc, R_G = 9.1 Ω) (Note 2)	$t_{d(on)}$	–	17	25	ns
Rise Time		t_r	–	137	160	
Turn–Off Delay Time		$t_{d(off)}$	–	38	45	
Fall Time		t_f	–	31	40	
Gate Charge	(V_{DS} = 48 Vdc, I_D = 15 Adc, V_{GS} = 10 Vdc) (Note 2)	Q_T	–	13.8	18.9	nC
		Q_1	–	2.8	–	
		Q_2	–	6.6	–	
SOURCE–DRAIN DIODE CHARACTERISTICS					
Forward On–Voltage	(I_S = 20 Adc, V_{GS} = 0 Vdc) (Note 2)	V_{SD}				Vdc
	(I_S = 20 Adc, V_{GS} = 0 Vdc, T_J = 125°C)		–	1.0	1.15	
			–	0.9	–	
Reverse Recovery Time	(I_S =15 Adc, V_{GS} = 0 Vdc, dI_S/dt = 100 A/μs) (Note 2)	t_{rr}	–	23	–	ns
		t_a	–	13	–	
		t_b	–	10	–	
Reverse Recovery Stored Charge		Q_{RR}	–	0.017	–	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
3. Switching characteristics are independent of operating junction temperature.

ORDERING INFORMATION

Device	Package	Shipping†
NTD20N03L27T4G	DPAK (Pb–Free)	2500 / Tape & Reel
NVD20N03L27T4G*	DPAK (Pb–Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NVD Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable.

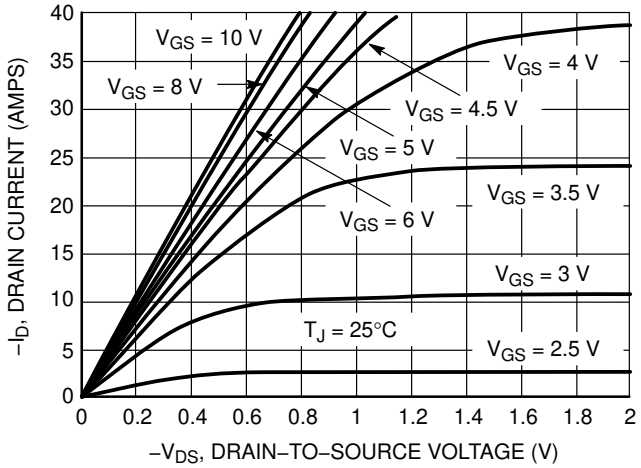


Figure 1. On−Region Characteristics

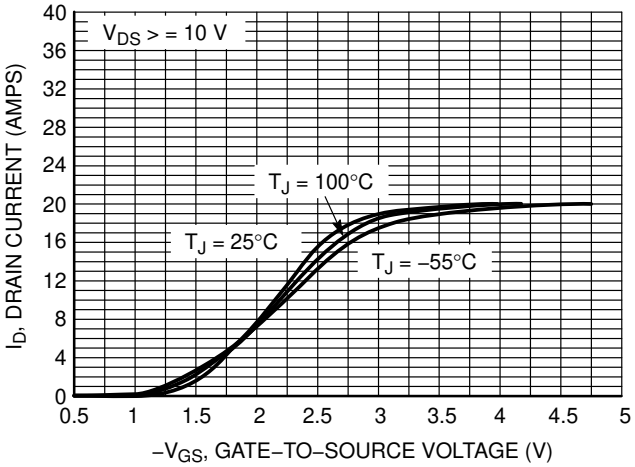


Figure 2. Transfer Characteristics

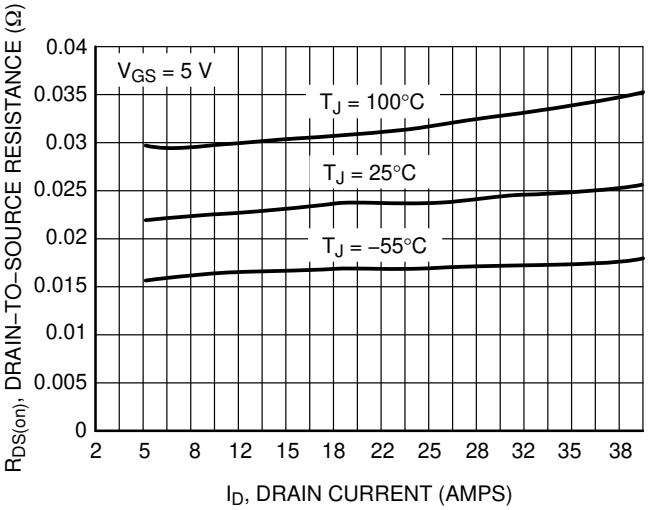


Figure 3. On−Resistance vs. Drain Current and Temperature

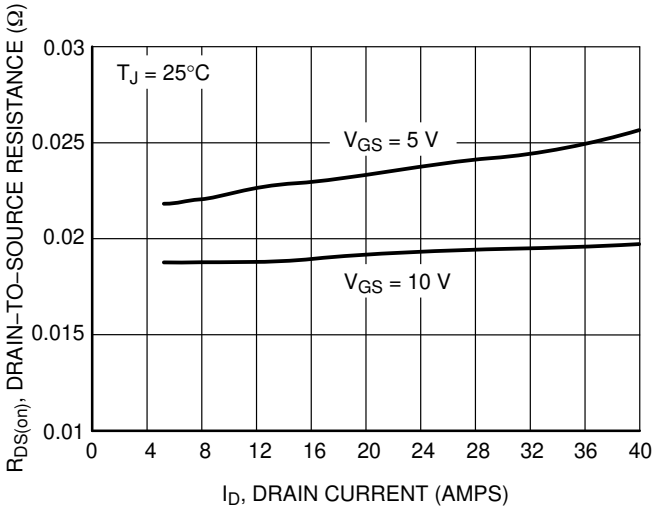


Figure 4. On−Resistance vs. Drain Current and Gate Voltage

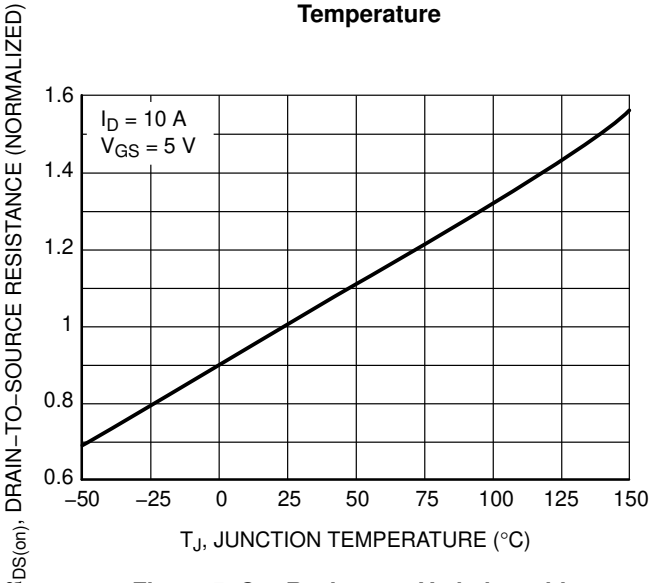


Figure 5. On−Resistance Variation with Temperature

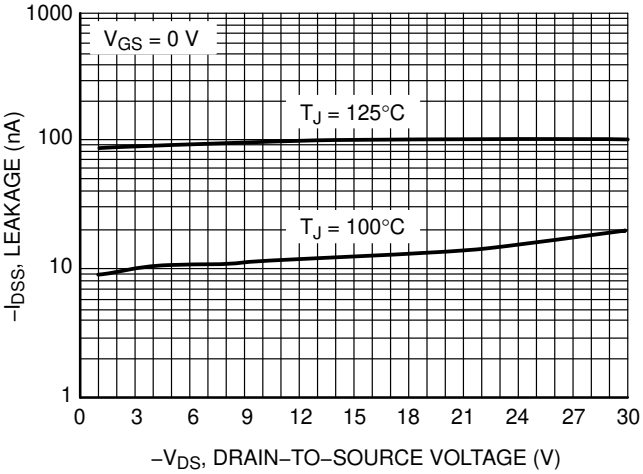


Figure 6. Drain−to−Source Leakage Current vs. Voltage

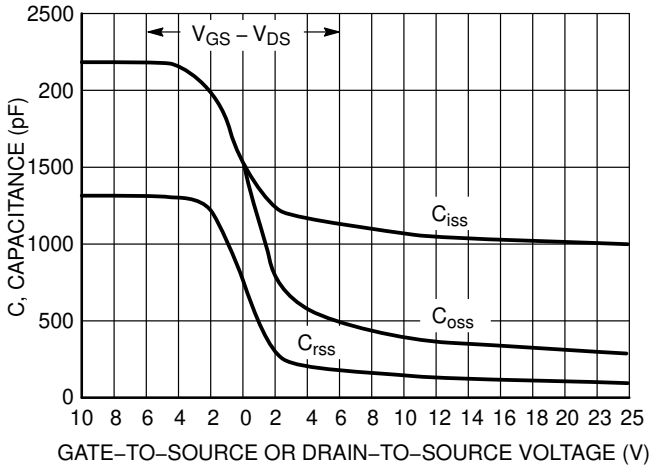


Figure 7. Capacitance Variation

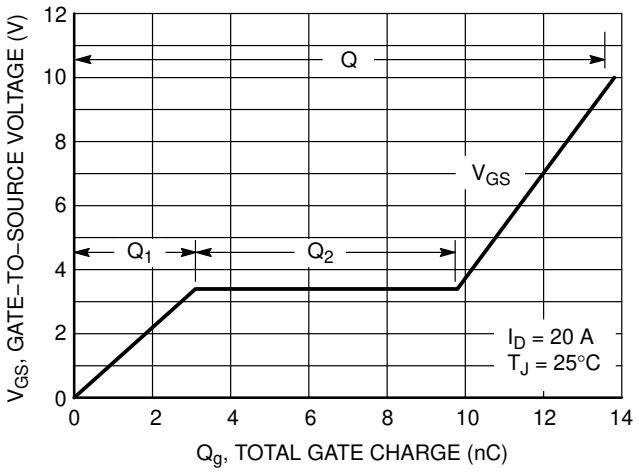


Figure 8. Gate–to–Source and Drain–to–Source Voltage vs. Total Charge

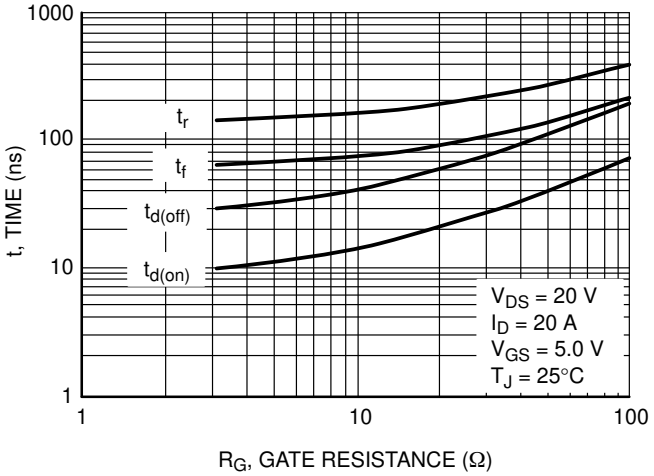


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

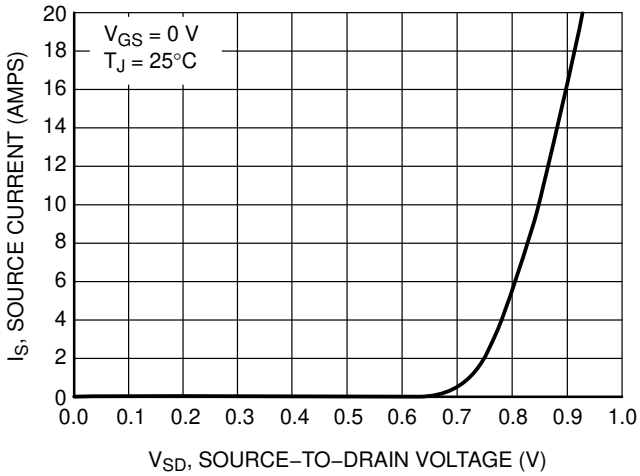


Figure 10. Diode Forward Voltage vs. Current

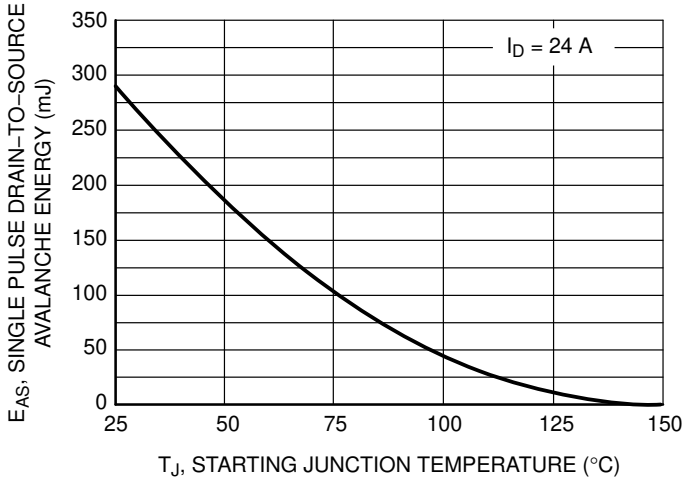
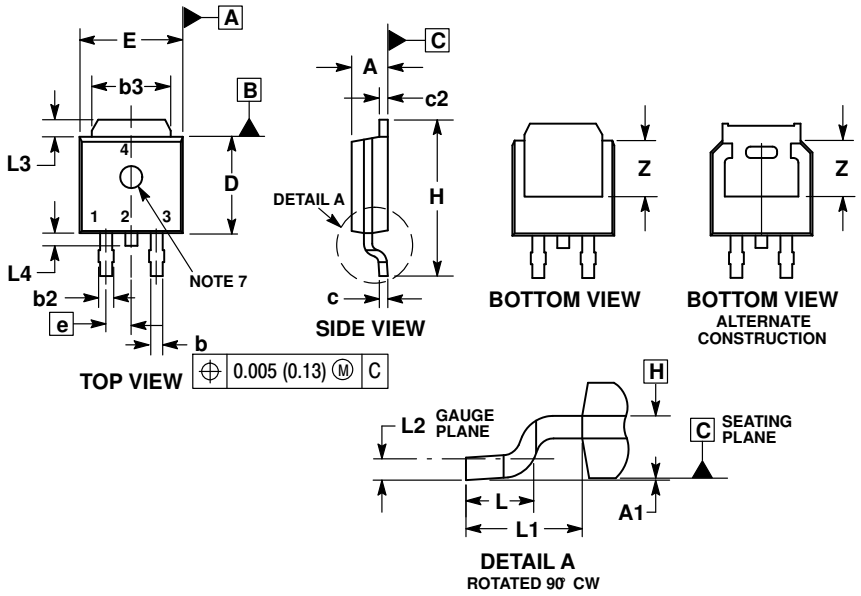


Figure 11. Maximum Avalanche Energy vs. Starting Junction Temperature

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE)
CASE 369C
ISSUE E

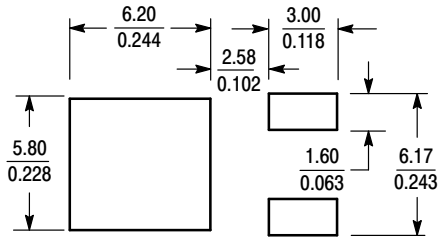


NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

SOLDERING FOOTPRINT*



SCALE 3:1 (mm / inches)

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada
Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada
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For additional information, please contact your local Sales Representative

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